## XMC ${ }^{\text {TM }}$ Link

## Based on SEGGER J-Link Technology

## About this document

## Scope and purpose

This is the user's manual for the $X M^{T M}$ Link also called isolated debug probe, providing technical information and hints on how to use it.

Intended audience
This document is intended for anyone who wants to use the XMC ${ }^{\text {TM }}$ Link.

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## 1 <br> Introduction

This document describes the features and hardware details of the $\mathrm{XMC}^{T M}$ Link. $\mathrm{XMC}^{\text {TM }}$ Link is an isolated debug probe for all XMC ${ }^{T M}$ microcontrollers.

The debug probe is based on SEGGER J-Link debug firmware, which enables use with DAVE ${ }^{\text {TM }}$ and all major third-party compiler/IDEs known from the wide ARM ${ }^{\circledR}$ ecosystem. Table 1 shows its specification.

Table $1 \quad$ XMC ${ }^{\text {TM }}$ Link specification

| Supported Processor | All Infineon Cortex ${ }^{\circledR}-\mathrm{M}$ based XMC $^{\text {TM }}$ Microcontroller |
| :--- | :--- |
| Dimensions | $62 \times 33 \mathrm{~mm}$ (without cables plugged in) |
| Power | PC side: 5 V via Micro-AB USB Connector |
|  | Target side: $2.5 \mathrm{~V}-5.5 \mathrm{~V}$ via one of the debug connector (VDD) |
| Connectors | - $10-$ pin Cortex ${ }^{\oplus}$ Debug Connector |
|  | - $8-$ pin XMC $^{\text {TM }}$ MCU Debug Connector |
|  | - Micro -AB USB Connector |
| Supported Protocols | - Serial Wire Debug (SWD) |
|  | - Single Pin Debug (SPD) |
|  | - Serial Wire Viewer (SWV via SWO pin) |
|  | - JTAG |
|  | - UART-to-USB Bride, Virtual COM (VCOM) |
| Others | - 1 kV functional isolation |

## $1.1 \quad$ Block diagram

The block diagram in Figure 1 shows the main components of the $\mathrm{XMC}^{\text {TM }}$ Link and their interconnections. There are following main building blocks:

- XMC4200 Microcontroller in a VQFN42 package
- Isolating Device
- 10-pin Cortex ${ }^{\circledR}$ Debug Connector
- 8-pin XMC ${ }^{\text {TM }}$ MCU Debug Connector
- Micro-AB USB Connector
- 2 LEDs: Debug LED and Communication LED
- 12 MHz Crystal


Figure 1 Block diagram of the $\mathrm{XMC}^{\text {TM }}$ Link

## $1.2 \quad$ Getting started

To operate the $X M C^{T M}$ Link the installation of the J-Link Driver is required.

1. Please download the latest version from https://www.segger.com/jlink-software.html and install it on your PC/laptop.

Note: The J-Link driver is also part of the typical installation of DAVE ${ }^{\text {TM }}$ and 3rd party tools supporting SEGGER JLink.
2. Connect $\mathrm{XMC}^{T M}$ Link with your PC/laptop using the Micro USB cable.
3. A proper connection and installation of the J-Link driver is indicated by a constantly illuminated DEBUG LED.
4. Connect your $\mathrm{XMC}^{T M}$ target board with $\mathrm{XMC}^{T M}$ Link using one of the enclosed cables.
5. Select SEGGER J-Link as debugger in your preferred IDE e.g. DAVE ${ }^{\text {TM }}$
6. Start the flash programming and debugging session

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## 2 Hardware description

The following chapters provide a detailed description of the hardware and how it can be used. The hardware is depicted in Figure 2.


Figure $2 \quad \mathrm{PCB}$ of the $\mathrm{XMC}^{\text {TM }}$ Link

## 2.1 <br> Known limitation

XMC Link ${ }^{\top M}$ V1 has a minor known limitation which could occur only during programming the BMI of a XMC1000 device in ASC-BSL mode to another BMI mode. This limitation is solved in the PCB version V1.1. The version number is printed on the bottom side of the PCB below the USB connector.

The limitation can be avoided if the $\mathrm{XMC}^{T M}$ Link V1 is powered before the target $\mathrm{XMC}^{\text {TM }}$ will be powered.

### 2.2 Debug connector

The $X M C^{T M}$ Link can be connected to the $X M^{T M}$ target microcontroller by either of the debug connectors:

- 8-pin XMC ${ }^{\text {TM }}$ MCU Debug Connector ( $2 \times 4$ pin, 0.1 ", 2.54 mm )
- 10-pin Cortex ${ }^{\text {TM }}$ Debug Connector ( $2 \times 5$ pin, 0.05 ", 1.27 mm )

The 8-pin XMC™ MCU Debug Connector is mainly used for the XMC1000 applications. The 10-pin Cortex ${ }^{\text {TM }}$ Debug Connector can be used for all XMC${ }^{\text {TM }}$ families but is focusing on the XMC4000 family supporting Serial Wire Viewer (SWV) via the SWO pin.

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The common debug protocol supported by both connectors is Serial Wire Debug (SWD). Figure 3 provides an overview on all supported debug protocols and communication channels.

|  | XMC1000 Family |  | XMC4000 Family |
| :---: | :---: | :---: | :---: |
|  | 8-pin $\mathrm{XMC}^{\text {TM }} \mathrm{MCU}$ <br> Debug Connector | 10-pin Cortex ${ }^{\text {TM }}$ <br> Debug Connector | 10-pin Cortex ${ }^{\text {TM }}$ <br> Debug Connector |
| Serial Wire Debug (SWD) | $\checkmark$ | $\checkmark$ | $\sqrt{7}$ |
| Single Pin Debug (SPD) | $\boxed{\square}$ | $\checkmark$ |  |
| Serial Wire Viewer (SWV/SWO) |  |  | $\checkmark$ |
| Virtual COM Port (UART-to-USB Bridge) | $\checkmark$ |  |  |
| JTAG |  |  | $\checkmark$ |

Figure 3 Supported debug protocols

### 2.2.1 Pinout of debug connectors

The pinout of both debug connectors and to which pins of the $\mathrm{XMC}^{\text {TM }}$ the debugger must be connected can be found in Table 2 and Table 3.

Table 2 Pinout of the 10-pin Cortex ${ }^{\text {TM }}$ debug connector

| Pin | Function | XMC1000 Connection (Pin name) | XMC4000 Connection (Pin name) |
| :--- | :--- | :--- | :--- |
| 1 | VCC | Power Supply 2.5 V - 5.5 V (VDD) | Power Supply VDDP 3.3 V (VDDP) |
| 2 | SWIO/TMS | Serial Wire Data (P0.14 $\mid$ P1.3) | Serial Wire Data, JTAG-TMS (TMS) |
| 3 | GND | Ground (VSS) | Ground (VSS) |
| 4 | SWCLK/TCK | Serial Wire Clock (P0.15 $\mid$ P1.2) | Serial Wire Clock, JTAG-TCK (TCK) |
| 5 | GND | Ground (VSS) | Ground (VSS) |
| 6 | SWO/TDO | Not connected | Serial Wire Output, JTAG-TDO (P2.1) (optional) |
| 7 | KEY | Not connected | Not connected |
| 8 | TDI | Not connected | JTAG-TDI (P0.7)(optional) |
| 9 | GNDDetect | Can be used to switch off an on-board debug probe (PORST\# of OBD) (optional) |  |
| 10 | RESET\# | Not connected | PORST\# (mandatory) |

Table 3 Pinout of the 8-pin XMC ${ }^{\text {TM }}$ MCU debug connector

| Pin | Function | XMC1000 Connection (Pin name) |  |
| :--- | :--- | :--- | :--- |
| 1 | SC | Serial Wire Clock (P0.15 $\mid$ P1.2) |  |
| 2 | SD | Serial Wire Data (P0.14 $\mid$ P1.3) | R1.0 |
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| Pin | Function | XMC1000 Connection (Pin name) |
| :--- | :--- | :--- |
| 3 | + | Power supply 2.5 V - 5.5 V (VDD) |
| 4 | 0 | Ground (VSS) |
| 5 | 0 | Ground (VSS) |
| 6 | + | Power supply 2.5 V - 5.5 V (VDD) |
| 7 | TX (PC-TX)) | Transmissstion line of PC/laptop, receive line of XMC ${ }^{\text {TM }}$ device (optional) |
| 8 | RX (PC-RX) | Receive line of PC/laptop, transmission line of of $\mathrm{XMC}^{\text {TM }}$ device (optional) |

## $2.3 \quad$ Power supply

XMC ${ }^{\text {TM }}$ Link is powered from the Micro USB plug and typically draws about 70 mA . The on-board voltage regulator IFX54441LDV33 generates the required 3.3 V for the XMC4200 microcontroller out of the 5 V USB voltage. The debug probe is not designed to provide power for the target device.

The target application must power the isolated part of the debugger. The isolated side the $\mathrm{XMC}^{\top M}$ Link draws a few mA of current from the target application.

## $2.4 \quad$ Virtual COM Port (UART-to-USB Bridge)

The 8-pin XMC ${ }^{\text {TM }}$ MCU Debug Connector supports communication between a PC/laptop and target XMC ${ }^{\text {TM }}$ device via Virtual COM Port (UART-to-USB Bridge). Therefore UART pins of the target XMC ${ }^{\text {TM }}$ device needs to be connected to TX/RX pins of the debug connector (see Table 3).

Note: $\quad$ Take care of the UART cross connection: TX pin of debugger needs to be connected to RX pin of the XMC device. RX pin of debugger needs to be connected to $T X$ pin of the XMC device.

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## $3 \quad$ Production data

This chapter covers schematics, board dimensions, component placement and the list of material.

## 3.1 <br> Schematics

Figure 4 shows the schematics of $X M C^{T M}$ Link V1 in hardware version 1.1.

### 3.1.1 Differences in hardware versions

In hardware version 1.1 compared to hardware version v1.0 (V1) the pull-down resistor R20 was added to the TX line. The version number is printed on the bottom side of the PCB below the USB connector.


Figure 4
Schematic of the XMC ${ }^{\text {TM }}$ Link V1 (Hardware Version 1.1)

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### 3.2 Components placement and geometry

Figure 5 shows the board dimensions and the placement of components on the PCB.


Figure 5 Components placement and geometry

## $3.3 \quad$ List of material

The list of material is valid for the $\mathrm{XMC}^{T M}$ Link V1 in hardware version 1.1.
Table 4 List of material

| Value | Device | Qty | Reference Designator |
| :--- | :--- | :--- | :--- |
| 15pF 50V 10\% 0402 | Capacitor COG | 2 | C5, C6 |
|  |  | 8 | C2, C3, C14, C15, C19, C23, C24, <br> C25 |
| 10uF 10V 20\% 0603 | Capacitor X5R |  | C4, C7, C8, C9, C10, C11, C12, <br> C16, C17, C18, C20, C21, C22 |
| 100 nF 16V 10\% 0402 | Capacitor X7R | 13 | C1 |
| 10nF 16V 10\% 0402 | Capacitor X7R | 1 | C13 |
| 4u7F 6.3V +-10\% 0603 | Capacitor X7R | Connector Micro USB AB SMD Hirose | 1 |
| ZX62-AB-5PA | Crystal 12MHz 4Pad NX3225SA NDK | 1 | Q1 |
| 12MHz 3.2x2.5 | Diode Protection Infineon | 1 | V2 |
| ESD8V0L2B-03L TSLP-3-1 | Ferrite Bead 60R 500mA Murata | 1 | L1 |
| BLM18PG600SN1D 0603 | 2 | U3, U6 |  |
| SI8652BB-B-IS1 NB-SOIC-16 | Isolation IC | 1 | LED1 |
| LSQ971-Z LED-GN 0603 | LED SMD gn | 1 | LED2 |
| LSQ976-Z LED-RT 0603 | LED SMD rt | 1 | U4 |
| 74LVC1G126GW TSSOP5 | Line Driver |  |  |
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| Value | Device | Qty | Reference Designator |
| :--- | :--- | :--- | :--- |
| SN74LVC1G07 SC70-5 | Line Driver | 1 | U5 |
| XMC4200-Q48K256 QFN48 | Microcontroller XMC4200 Infineon | 1 | U2 |
| FTS-105-01-L-DV 2x5pin |  |  | X1 |
| 0.05" | Pin Header SMD Samtec | 1 |  |
| TSM-104-01-F-DH-A 2x4pin |  | 1 | X2 |
| $0.1 "$ | Pin Header SMD Samtec | 1 | X4 |
| no ass. 1x5pin 0.1" | Pin Header THT | 7 | R12, R13, R14, R15, R16, R17, R18 |
| 100R 1\% 0402 | Resistor | 3 | R9, R10, R11 |
| 100k 1\% 0402 | Resistor | 3 | R7, R20, R21 |
| 10k 1\% 0402 | Resistor | 1 | R8 |
| 1M 1\% 0603 | Resistor | 2 | R3, R5 |
| 22R 1\% 0402 | Resistor | 1 | R6 |
| 4k7 1\% 0402 | Resistor | 1 | R4 |
| 510R 1\% 0402 | Resistor | 2 | R1, R2 |
| 680R 1\% 0603 | Resistor | 1 | R19 |
| no ass. 0R 0603 | Resistor | 1 | U1 |
| IFX54441LDV33 PG-TSON-10 | Voltage Regulator 3.3 V Infineon |  |  |

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Revision history

## Revision history

Major changes since the last revision

| Page or reference | Description of change |
| :--- | :--- |
|  |  |
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Edition 2015-12-11

## Published by

Infineon Technologies AG
81726 Munich, Germany
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## Document reference <br> UG_201512_PL30_004

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